

Wurth Electronics (UK) Ltd



Practical EMI Filter Design Considerations – Part 1

19th September 2017

Presented by

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Field Application Engineer - UK

Agenda



- Magnetics and Materials
- EMI Transmission Modes and Filter Topologies
- REDEXPERT
- Practical EMI Filter Design Considerations



MAGNETICS AND MATERIALS

What is an Inductor?



- ... technical aspect
- a piece of wire wrapped on something

We also see inductance ...

- as parasitic effects
 - What are the main difference between these inductors?

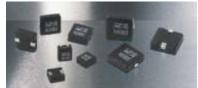










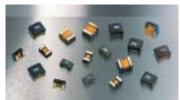






THE INDUCTOR IS USED TO STORE THE ENERGY

- DC/DC converter topology
 - Buck
 - Boost
 - Sepic





Inductors/Ferrites



- Shape & size : Different construction
 - THT, or SMT
 - Toroidal , Solenoidal (Rod core), Multilayer
 - Shielded or not shielded
 - Wire (Round, Flat, Multi-wire,..)







- Different material
 - NiZn
 - MnZn
 - Iron alloy
 - Superflux
 - WE-Perm
 - WE-Perm2
 - Iron Powder



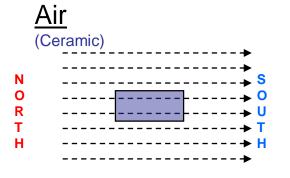




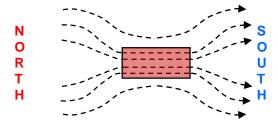


Core Material - Permeability





Rod core ferrite



material-

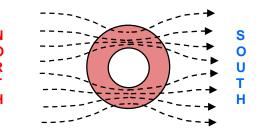
current-

Pressure-

frequency-

temperature-

Ring core ferrite



Induction in air:

$$B = \mu_0 \cdot H$$

linear function, because $\mu r = 1 = constant!$

The relative permeability is a:

Induction in a ferrite:

$$B = \mu_0 \cdot \mu_r \cdot H$$





-dependent parameter

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Core Material - Permeability



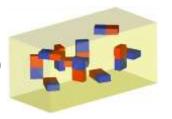
Relative permeability

 describes the capacity of concentration of the magnetic flux in the material

$$\mu_r = \frac{1}{\mu_0} \frac{\Delta B}{\Delta H}$$

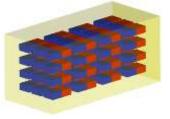
Ferrite material

- unordered (random position)
- soft magnetic



Permanent magnet

- ordered
- hard magnetic



Typical permeability μ_r:

Iron Powder/ Superflux: 50 ~ 150

Nickel Zinc (NiZn): 40 ~ 1500

Manganese Zinc (MnZn): 300 ~ 20000

Core Material – Permeability

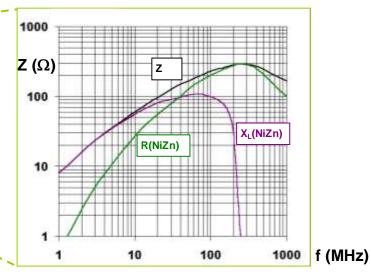




=1 turn



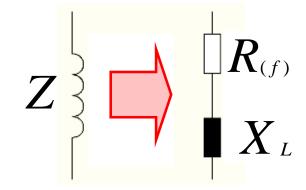




Core material-Parameter

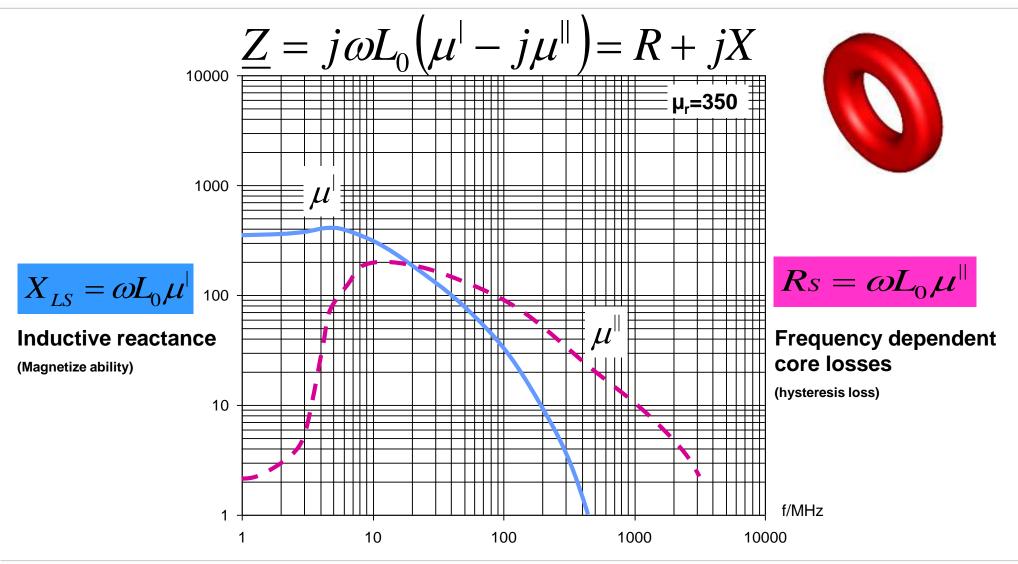
Replacement circuit

$Z = \sqrt{R_{(f)}^2 + X_L^2}$



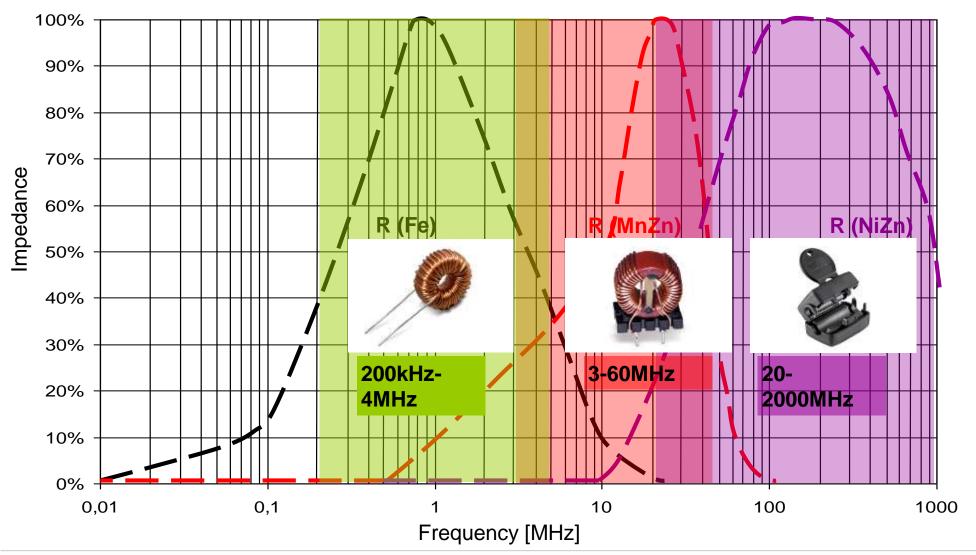
Core Material – Permeability





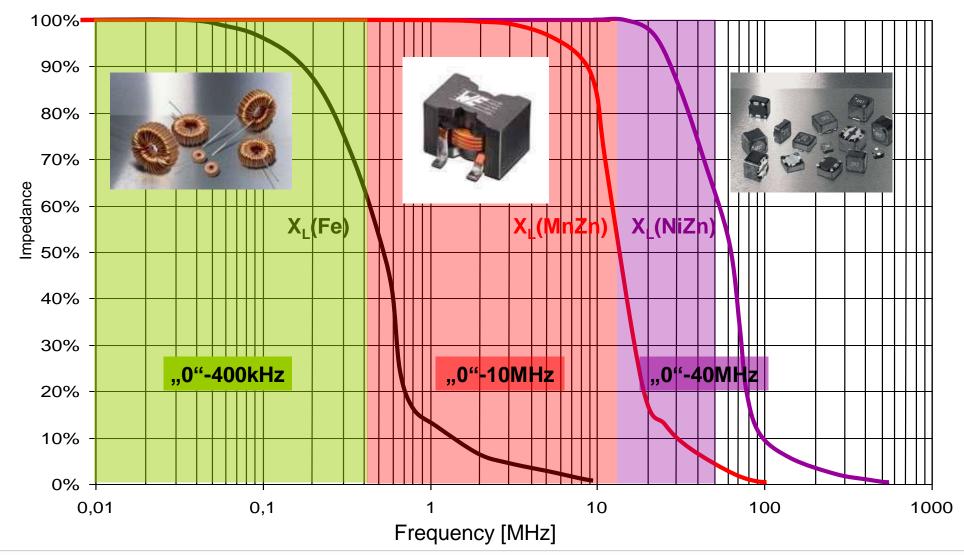
Core Material – Resistance





Core Material – Inductance





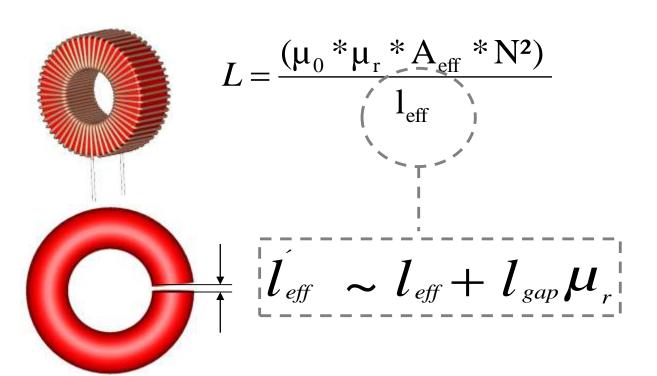
Core Material – Saturation/Frequency



Core Materials	Core Loss	Perm f(DC bias)	Relative Cost	Frequency Range	Saturation Flux density (B _{sat})	Temp Stability
Iron Powder	Highest	-	Lowest	200kHz	15.000 Gauss (1,5 Tesla)	-
Ni Zn	Lowest	_	Low	10MHz	4.500 Gauss (0,45 Tesla)	-
WePerm	Low	++	Low	3 MHz	10.000 Gauss (1.0 Tesla)	++
SuperFlux	Medium	+++	Medium	1.0 MHz	12.000 Gauss (1,2 Tesla)	+++

Switching Frequency ⇔ Core Material

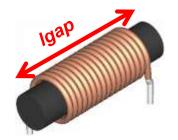
INDUCTOR / inductance

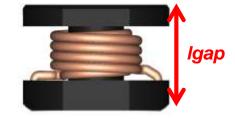


= relative permeability

= No. of turns

= effective magnetic area = effective magnetic length







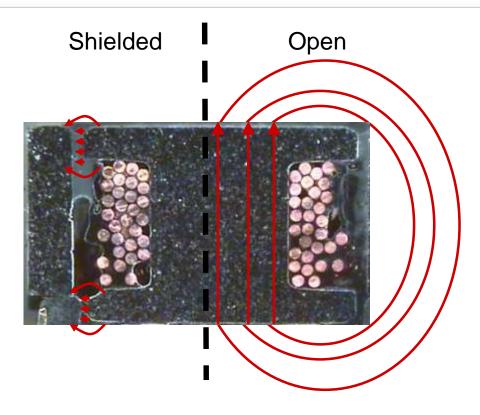


Higher leff Lower L



Core Material – Shielding





Advantage of the shielded inductor => smaller Gap

- ⇒ Less turns to reach the L value => Lower DCR compare to a open version
 - ⇒ With big air gap the inductance is less dependent of the core material



EMI TRANSMISSION MODES AND FILTER TOPOLOGIES

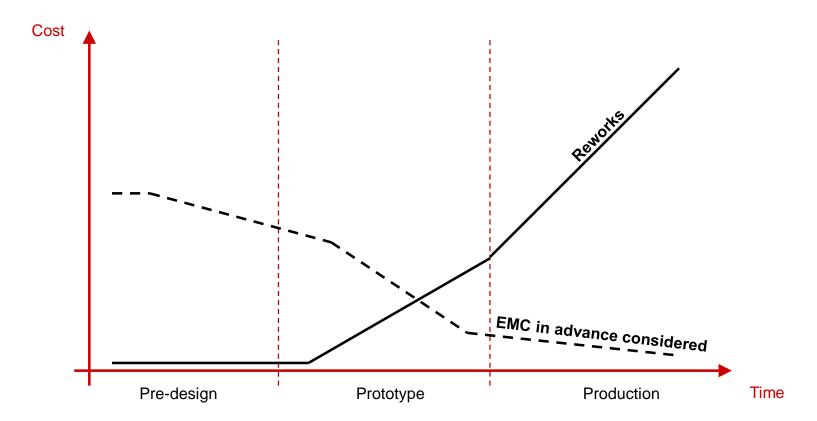
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EMC Impact



Economical point of view:

Dependent on when EMC conformity is considered in a design phase



What causes EMI in a product?



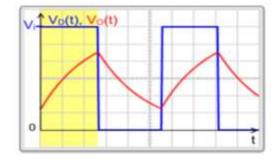
Clock frequencies. E.g Crystal 25MHz,
 CPU 2.6GHz

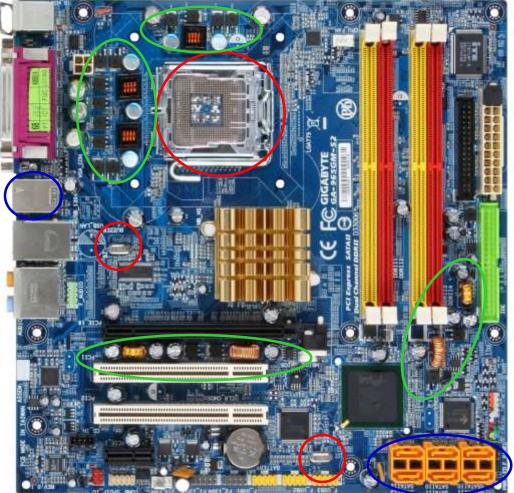


Data rates. E.g USB 2.0 480Mbps, SATA II 300Mbps



 DC/DC convertors and Switch mode power supplies (SMPS) E.g 135kHz, 2MHz





Transmission modes



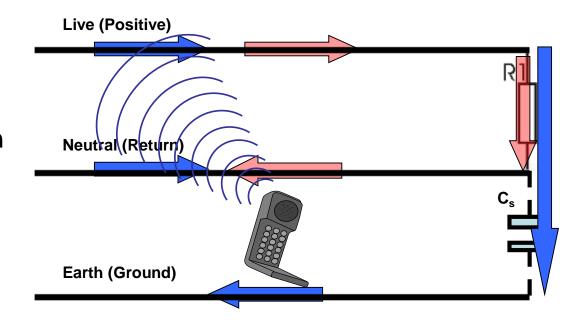
Recognize the transmission mode:

Differential Mode (DM)

Signals on a line(s) with a return path

Common Mode (CM)

Noise on all lines propagating in the same direction with respect to earth



EMC – Coupling



→ Primary procedure

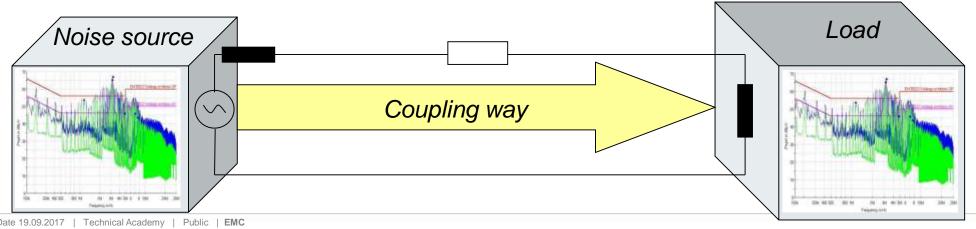
...to aim to source a low noise

→ Secondary procedure

... eliminate the noise through interrupting the coupling way

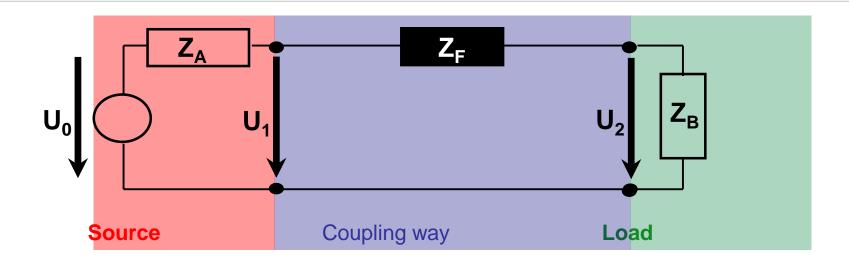
→ Tertiary procedure

... increase the noise immunity at load



Insertion loss – Mathematical Definition





System attenuation

$$A = 20 \cdot \log \frac{Z_A + Z_F + Z_B}{Z_A + Z_B}$$

Impedance

$$Z_F = \left[10^{\frac{A}{20}} \cdot \left(Z_A + Z_B\right)\right] - \left(Z_A + Z_B\right) \quad in \ (\Omega)$$

Insertion loss – Differential Filter Topologies



Source Impedance

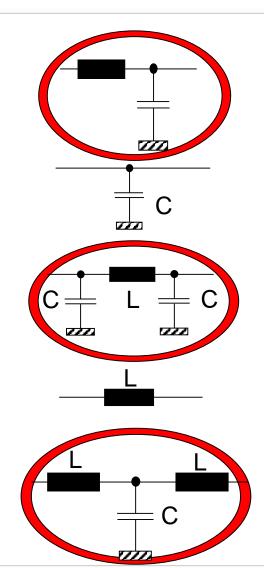
low

high

high or unknown

low

low or unknown



Load Impedance

high

high

high or unknown

low

low or unknown

→ small C = higher SRF

Choose ferrite bead

= build no resonance with C

= broadband filter

Pay attention to: SRF of used components

Filter topologies – Demo board



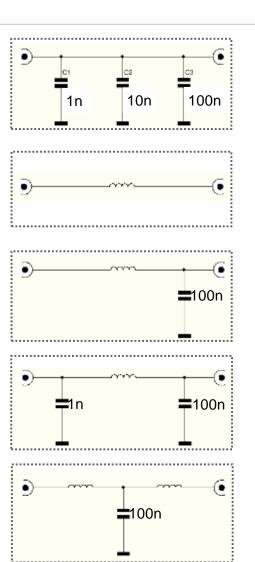
Parallel-C-filter

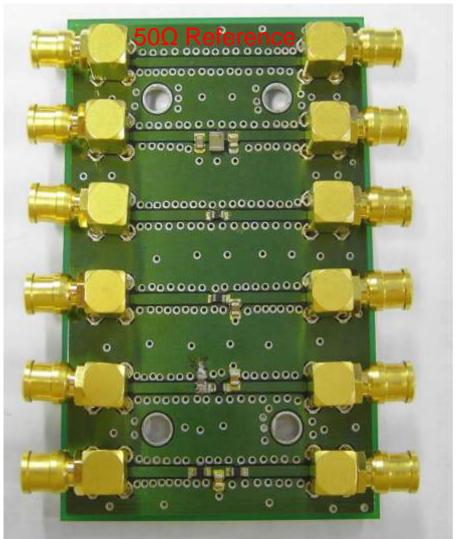
L-filter

LC-filter

• Π-filter

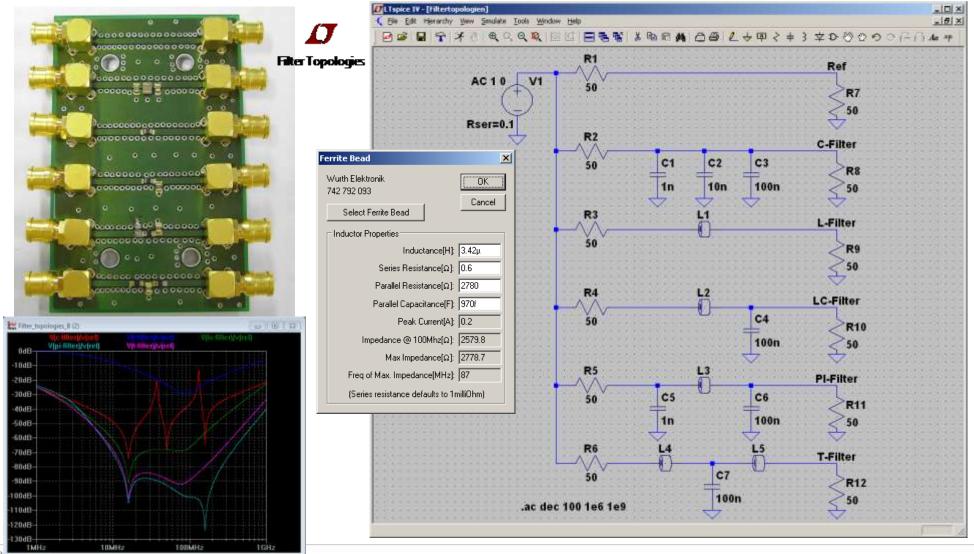
T-filter





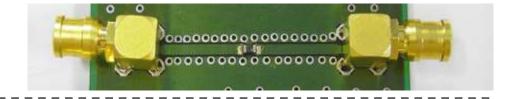
Filter Topologies – LT Spice Simulation







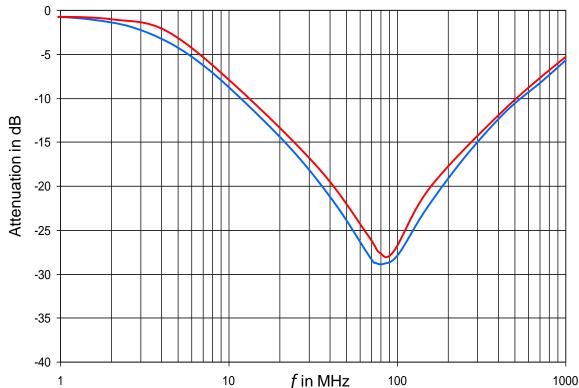
L-filter



- A chip bead ferrite is used as an inductance.
- WE-CBF 742 792 093:

$$Z_{\text{max}} = 3000\Omega @ 80MHz$$

$$A = -29 dB @ 80 MHz$$



Simulated

Measured

Filter topologies – Parallel-C-filter



Parallel-C-filter

100n

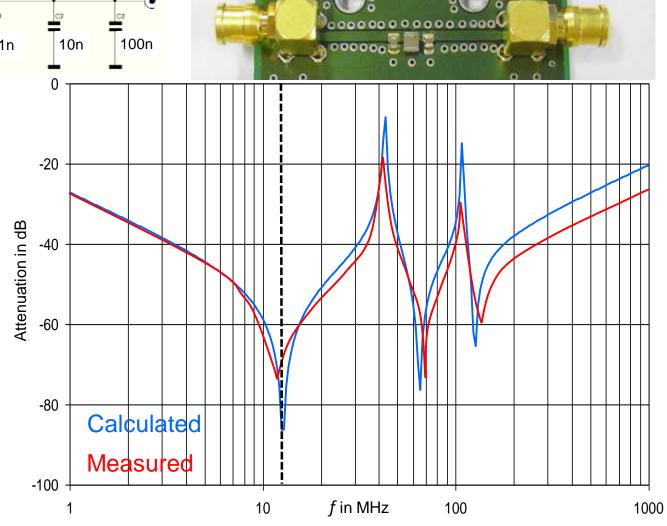
 Comparison of measurement and simulation

$$f_{\rm res} = \frac{1}{2\pi \cdot \sqrt{L_{\rm s} \cdot C}}$$

Example:

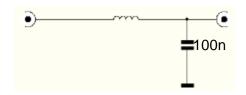
$$L_{\rm s} = 1 {\rm nH}$$

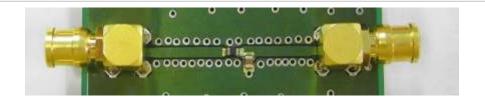
$$f_{\text{res,C3}} = 15.915 \text{MHz}$$





LC-filter

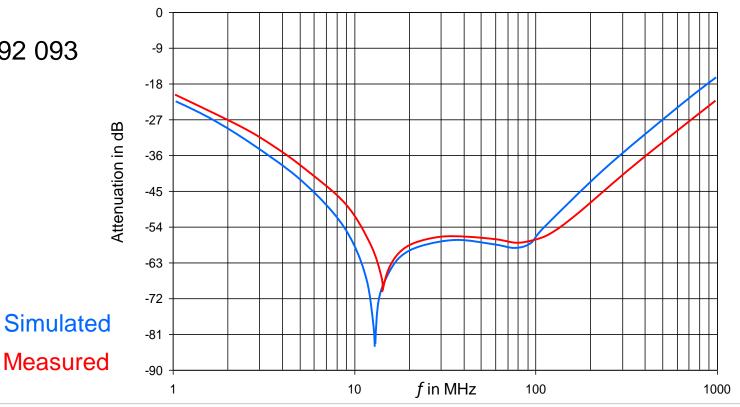




Comparison of measurement and simulation

WE-CBF 742 792 093

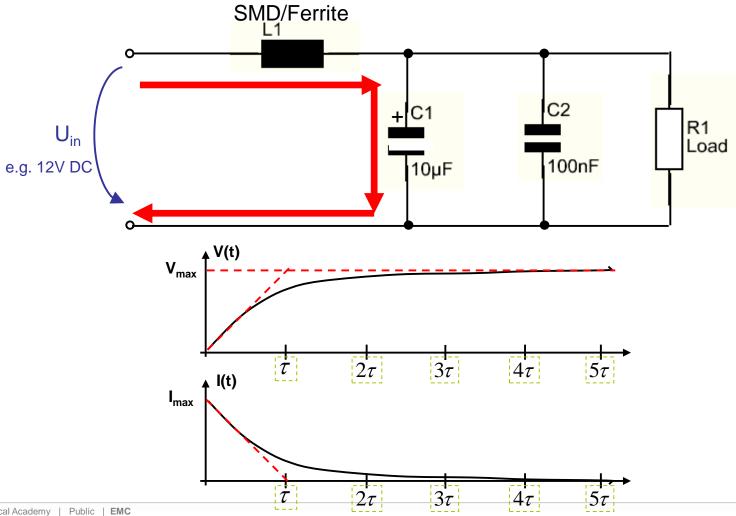
C = 100 nF



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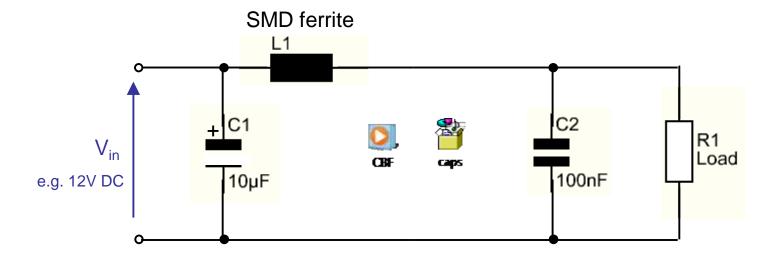


Avoiding inrush current damage to SMD ferrite beads





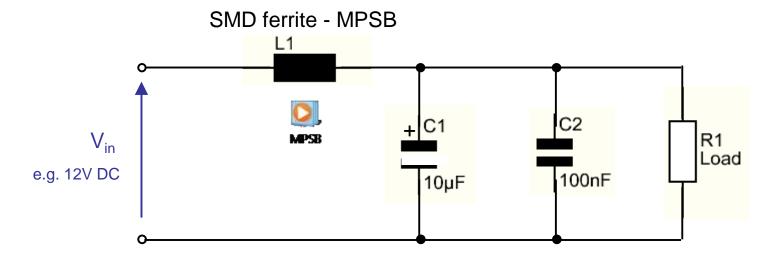
Avoiding inrush current damage to SMD ferrite beads – Option 1



- Safety for SMD ferrite against inrush/pulse current
- Not a PI-Filter



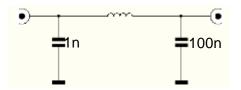
Avoiding inrush current damage to SMD ferrite beads – Option 2



- Use inrush current (pulse) rated SMD ferrite (WE-MPSB)
- Preferred solution as:
 - High impedance termination



• π-filter



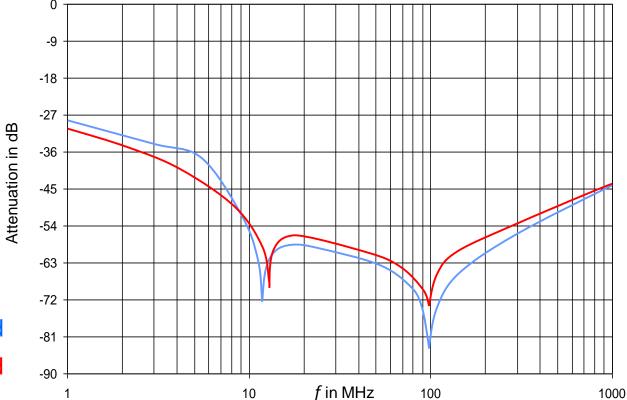


Comparison of measurement and simulation

WE-CBF 742 792 093

 $C_1 = 1nF$

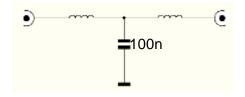
 $C_2 = 100 nF$

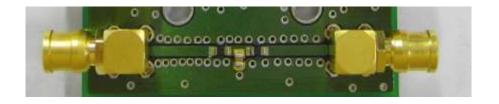


Simulated Measured



T-filter



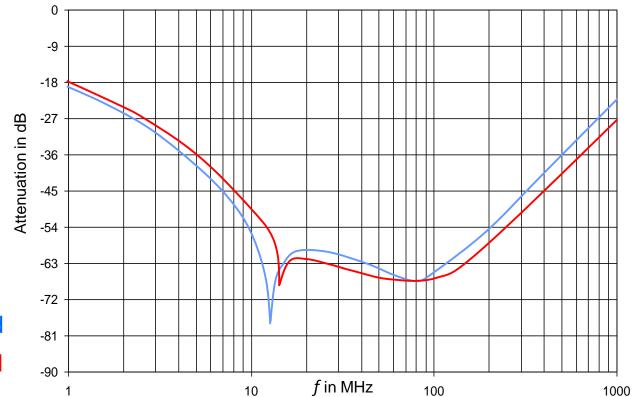


Comparison of measurement and simulation

WE-CBF 742 792 040

WE-CBF 742 792 093

C = 100nF

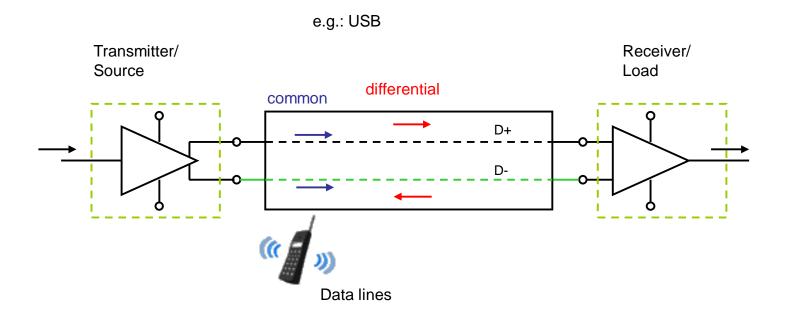


Simulated Measured

Common Mode – Signal propagation



Noise mode:



- Common mode noise
- Differential mode noise

Common Mode Choke – Principle of Operation



It is a Bi-directional filter

- From device to outside environment
- From outside environment to inside device

Intended Signal - Differential mode

Interference Signal (noise) – Common Mode

Conclusion:

- "almost" no affect the signal Differential mode
- high attenuation to the interference signal (noise) Common Mode

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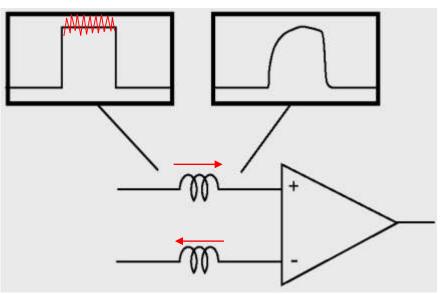
Common Mode Choke – Advantages



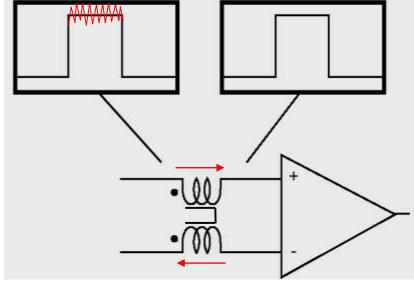
Filter with two inductors

Filter with CMC

Filter input Filter output



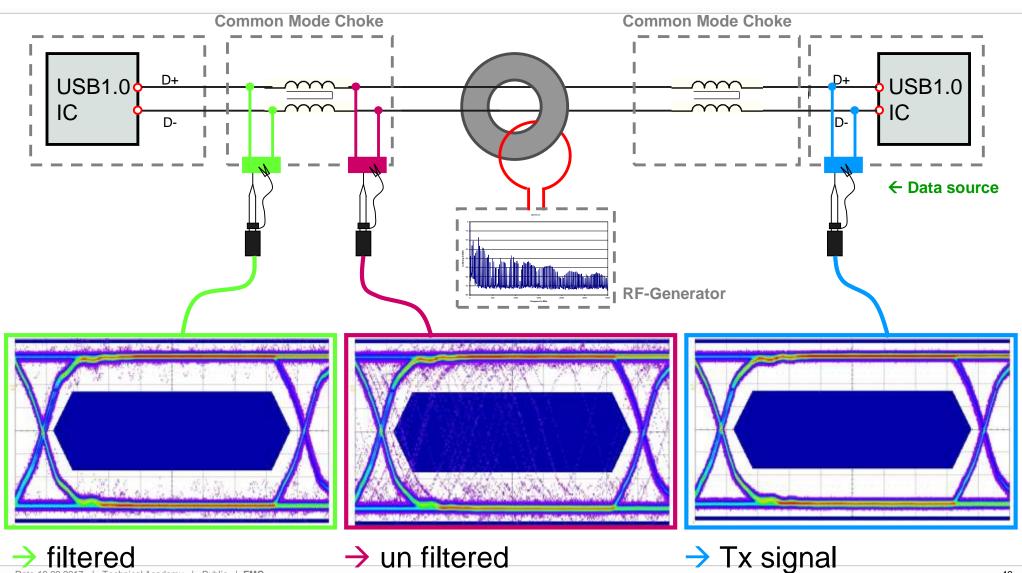
Filter input Filter output



- Signal not affected
- Noise attenuated even close to the signal frequency

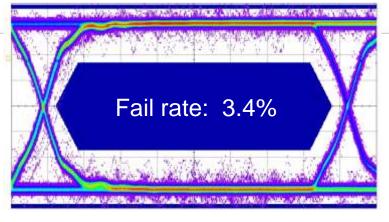
Common Mode Choke – USB application



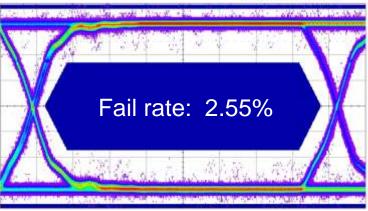


Common Mode Choke – USB application





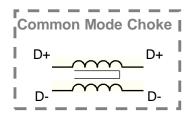
Increase Z



 $CM \rightarrow 32 \text{ Ohm}$ DM $\rightarrow 0.7 \text{ Ohm}$

@ 12 MHz

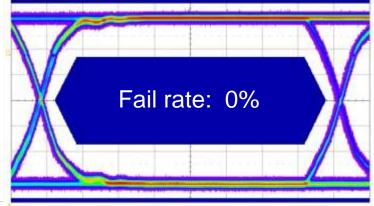
 $CM \rightarrow 363 \text{ Ohm}$ $DM \rightarrow 1 \text{ Ohm}$ @ 12 MHz



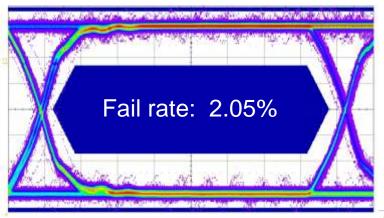
 $CM \rightarrow 41 \text{ Ohm}$ $DM \rightarrow 0.7 \text{ Ohm}$ @ 12 MHz

 $CM \rightarrow 77 \text{ Ohm}$ $DM \rightarrow 1 \text{ Ohm}$

@ 12 MHz



Increase Z

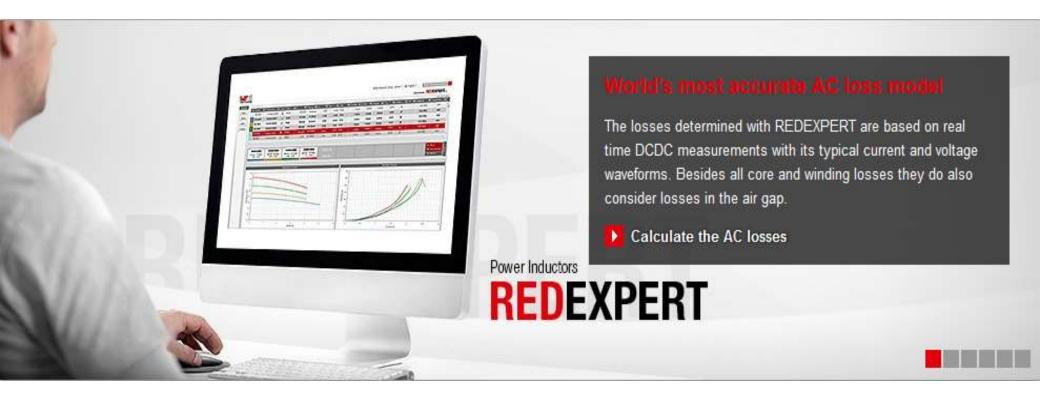




REDEXPERT

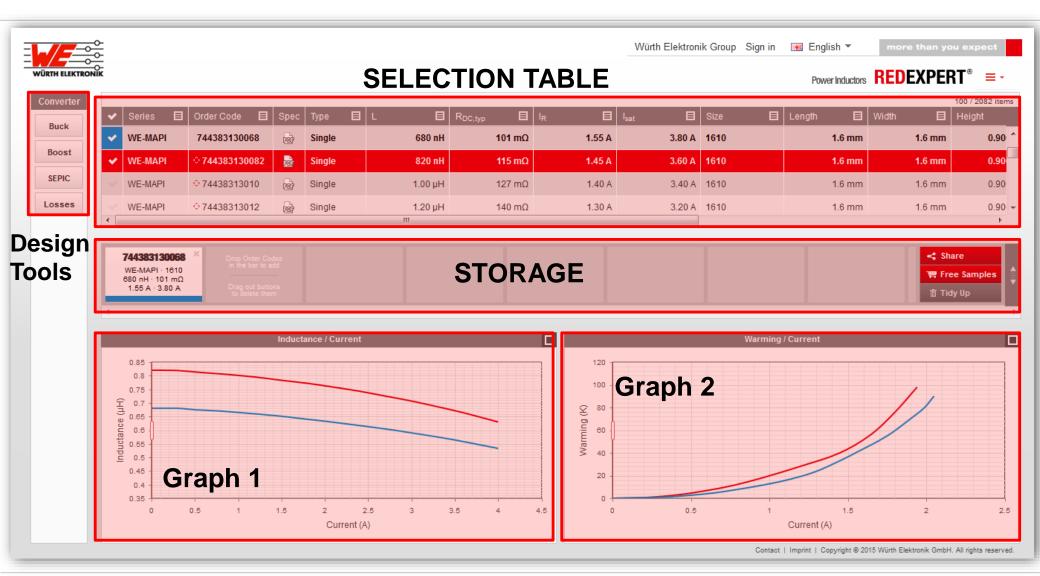


REDEXPERT



User Interface









www.we-online.com/redexpert

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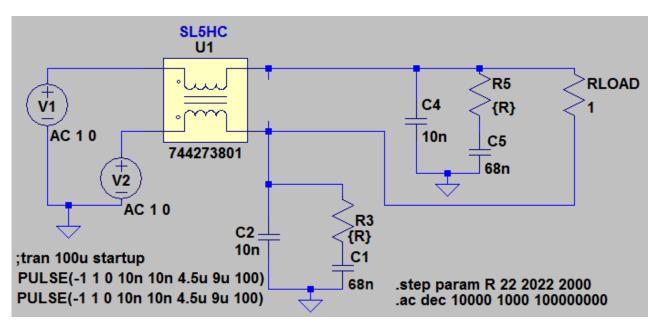
PRACTICAL EMI FILTER DESIGN CONSIDERATIONS

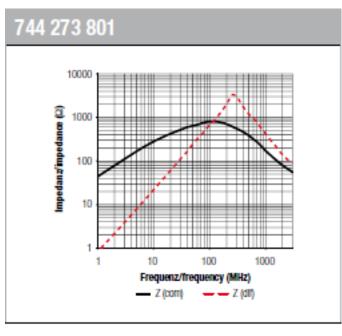
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Common Mode Filter Design



With Chassis / EMC Ground





- Power Supply Switching Frequency Considerations (L)
- EMI Higher Frequency Considerations (Z)
- Layout and Tracking
- Capacitor with and without Damping

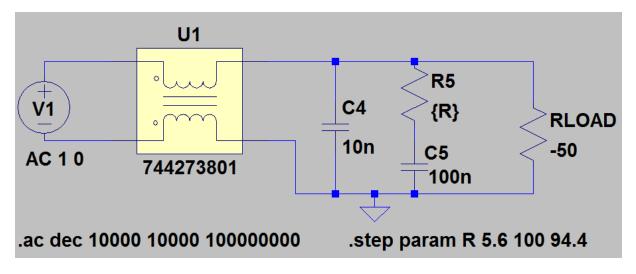




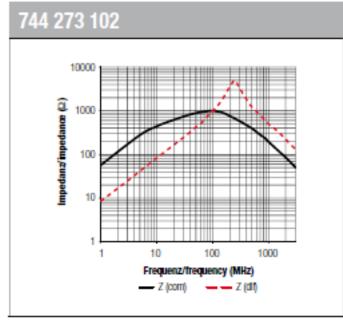
Common Mode Filter Design



DM (Leakage) Effect



- Load Impact
- Capacitor Damping

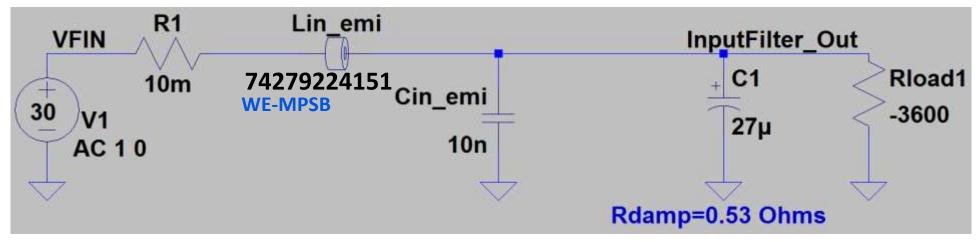






Differential Mode Filter Design – Input

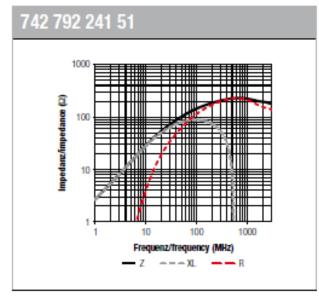




- Load Impact
- EMI Higher Frequency Considerations
- Pulse Rating (WE-MPSB)
- Layout and Tracking
- Capacitor Damping and Stability

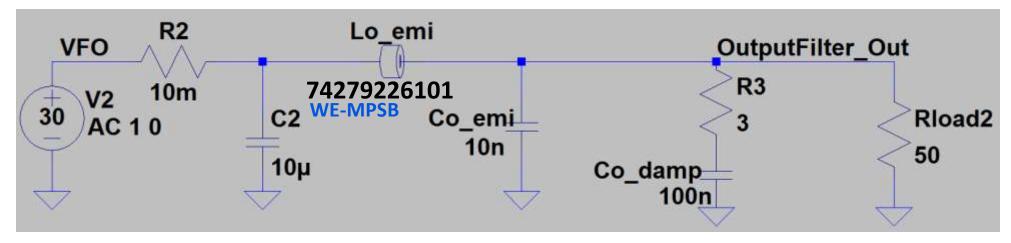






Differential Mode Filter Design – Output

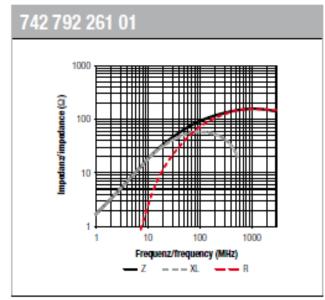




- Load Impact
- EMI Higher Frequency Considerations
- Pulse Rating (WE-MPSB)
- Layout and Tracking
- Capacitor Damping

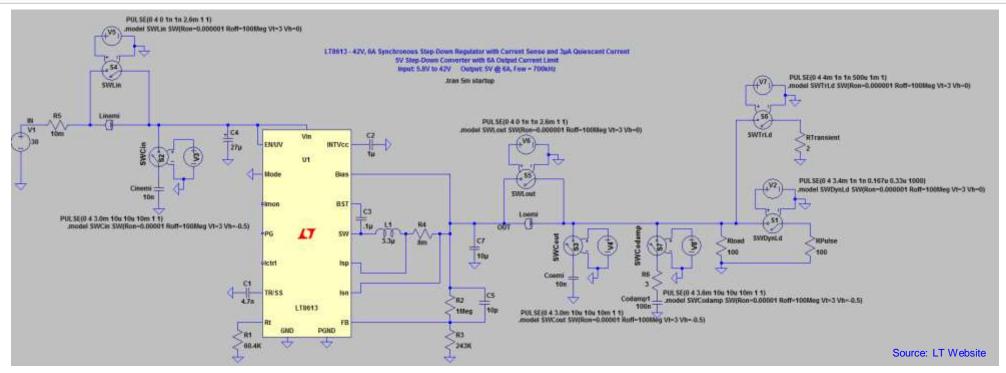






Differential Mode Filter Design – Buck Example





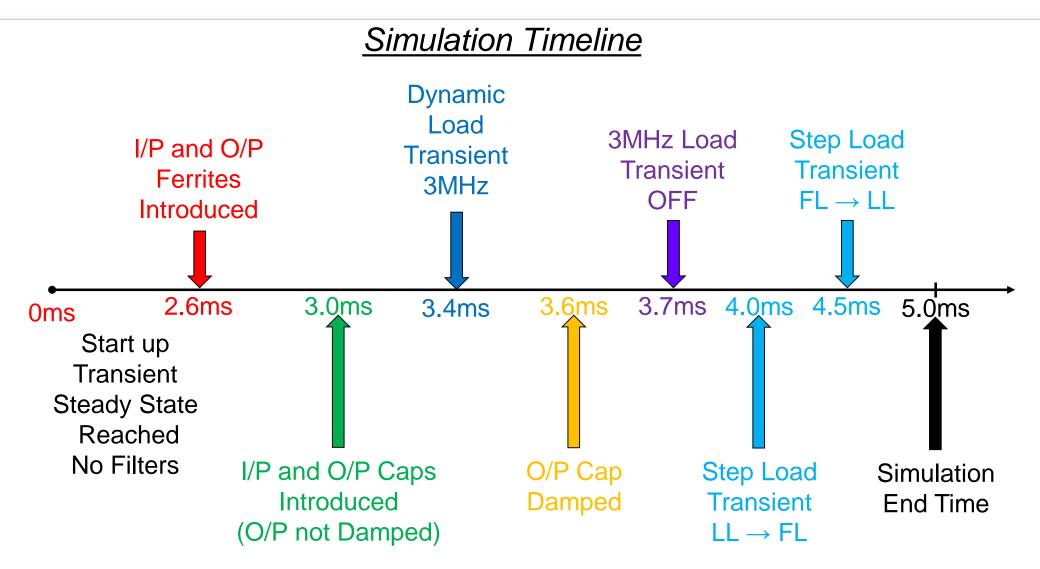
Start Up Conditions:

- No EMI Filters on I/P or O/P
- Max Vin = 30V
- Vout = 5V, Min Load 50mA (DCM)
- Actual filter component models used (no ideals)



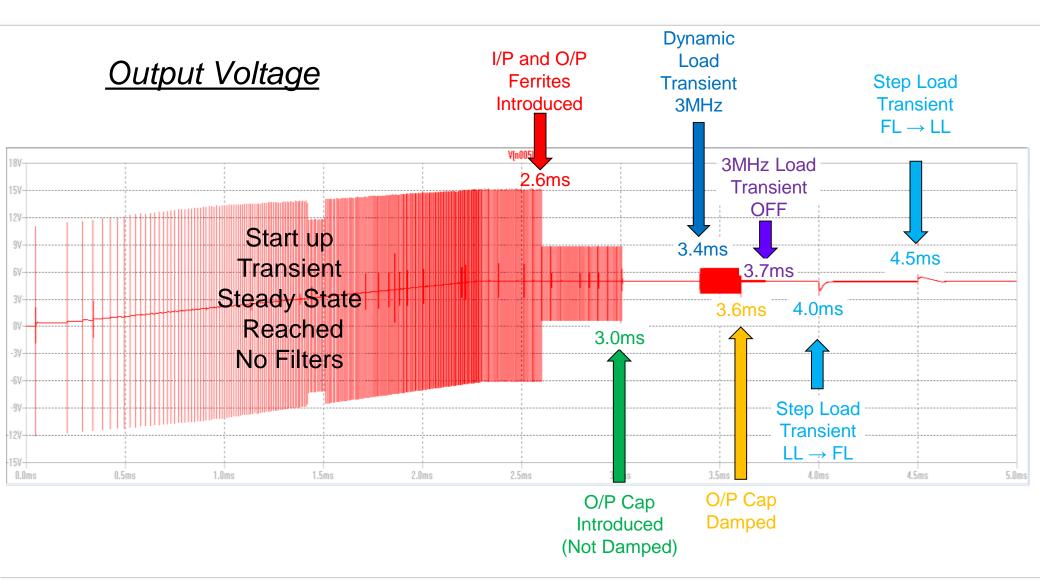
Differential Mode Filter Design – Buck Example

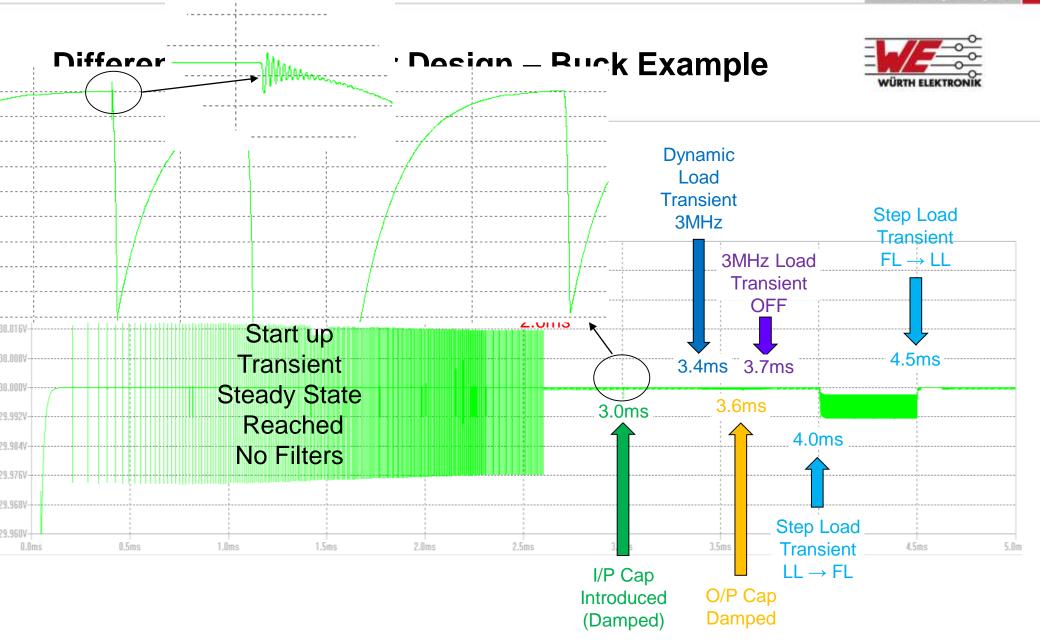




Differential Mode Filter Design – Buck Example

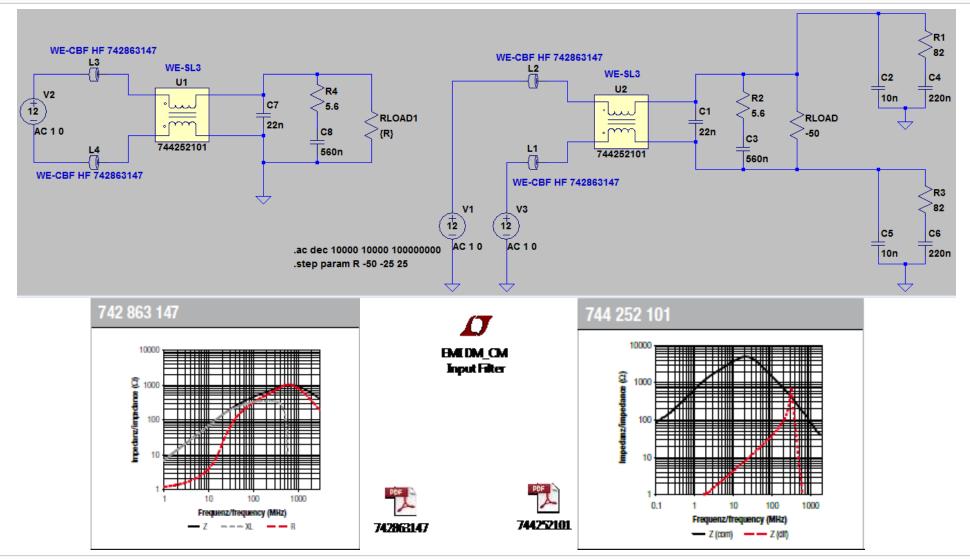






EMI Filter Design – Recommended Architecture





Thank you



Any Questions



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